



## Material Content Data Sheet



<b>Sales Product Name</b>		ISO1H801G		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA002441140						
<b>Package</b>		PG-DSO-36-21		<b>Weight*</b>		2104.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	16.733	0.80	0.80	7950	7950
chip_2	inorganic material	silicon	7440-21-3	1.164	0.06	0.06	553	553
chip_3	inorganic material	silicon	7440-21-3	1.123	0.05	0.05	533	533
leadframe	inorganic material	phosphorus	7723-14-0	0.388	0.02		185	
	non noble metal	zinc	7440-66-6	1.553	0.07		738	
	non noble metal	iron	7439-89-6	31.066	1.48		14760	
wire	non noble metal	copper	7440-50-8	1261.410	59.94	61.51	599337	615020
	noble metal	gold	7440-57-5	3.852	0.18	0.18	1830	1830
	encapsulation	organic material	carbon black	1333-86-4	1.523	0.07		723
encapsulation	plastics	epoxy resin	-	70.043	3.33		33280	
	inorganic material	silicondioxide	60676-86-0	689.774	32.77	36.17	327734	361737
leadfinish	non noble metal	tin	7440-31-5	15.044	0.71	0.71	7148	7148
plating	noble metal	silver	7440-22-4	0.644	0.03	0.03	306	306
solder	noble metal	silver	7440-22-4	0.101	0.00		48	
	non noble metal	lead	7439-92-1	0.151	0.01		72	
glue	non noble metal	tin	7440-31-5	9.819	0.47	0.48	4665	4785
	plastics	Polyimide	26023-21-2	0.290	0.01	0.01	138	138
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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